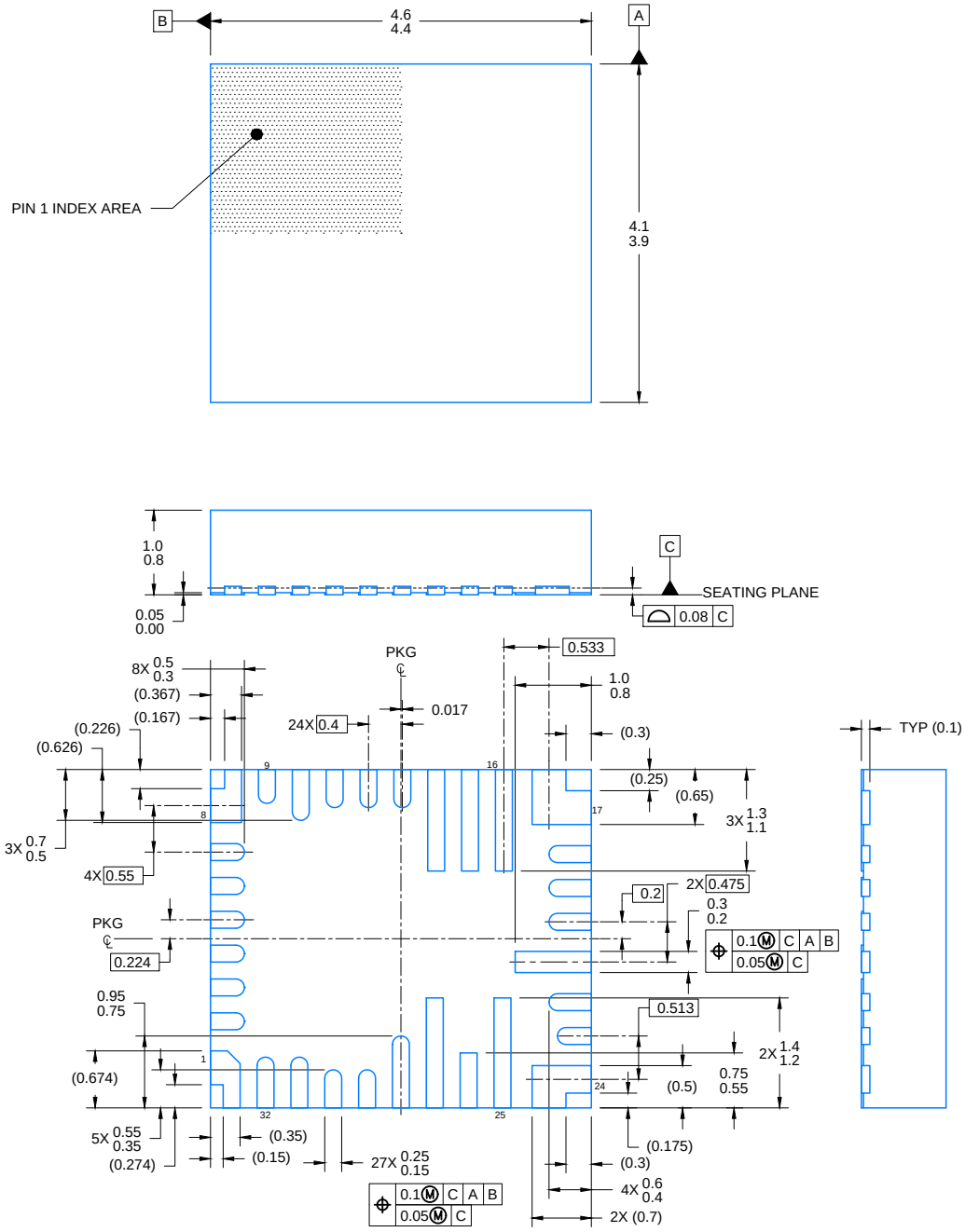
PACKAGE OUTLINE

RPP0032B

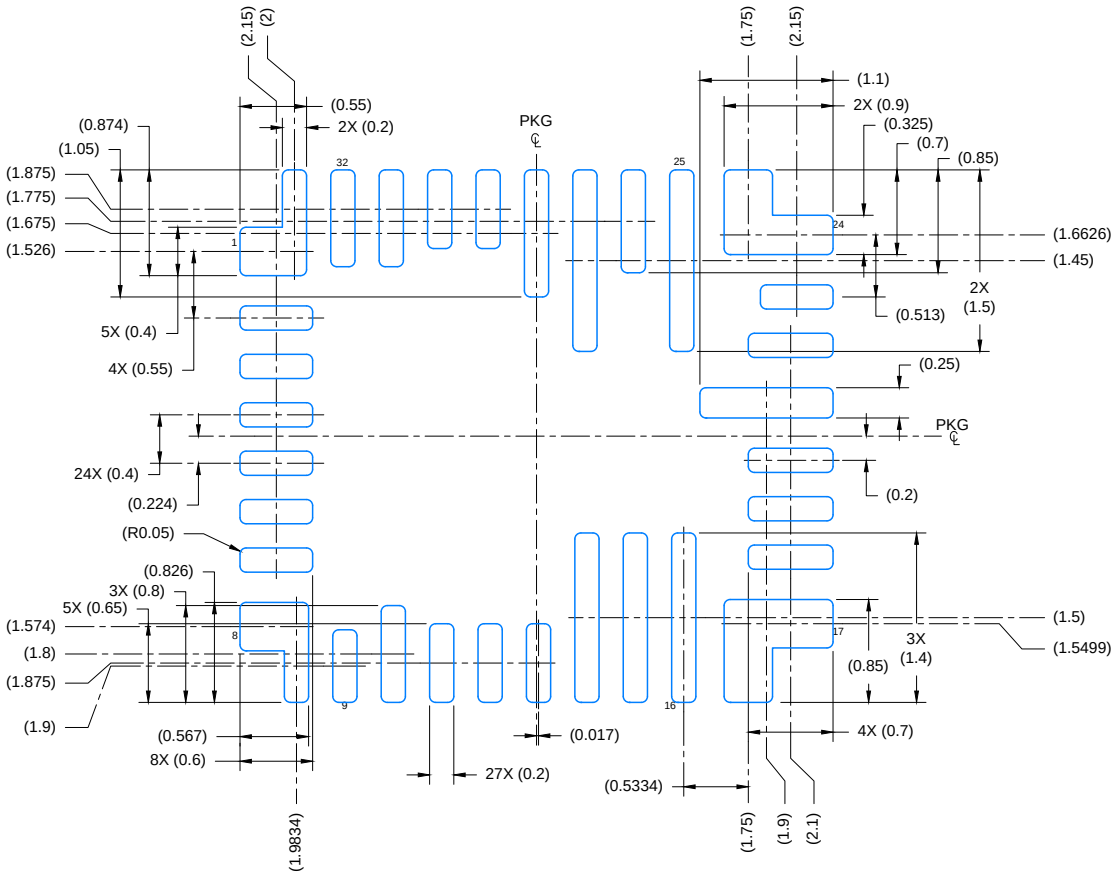
VQFN-HR - 1.0 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD

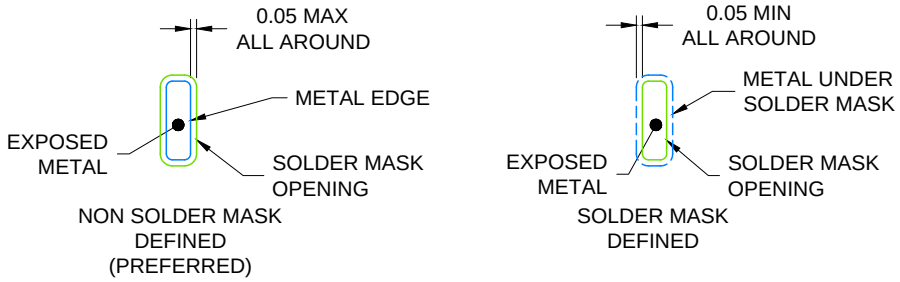


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 16X

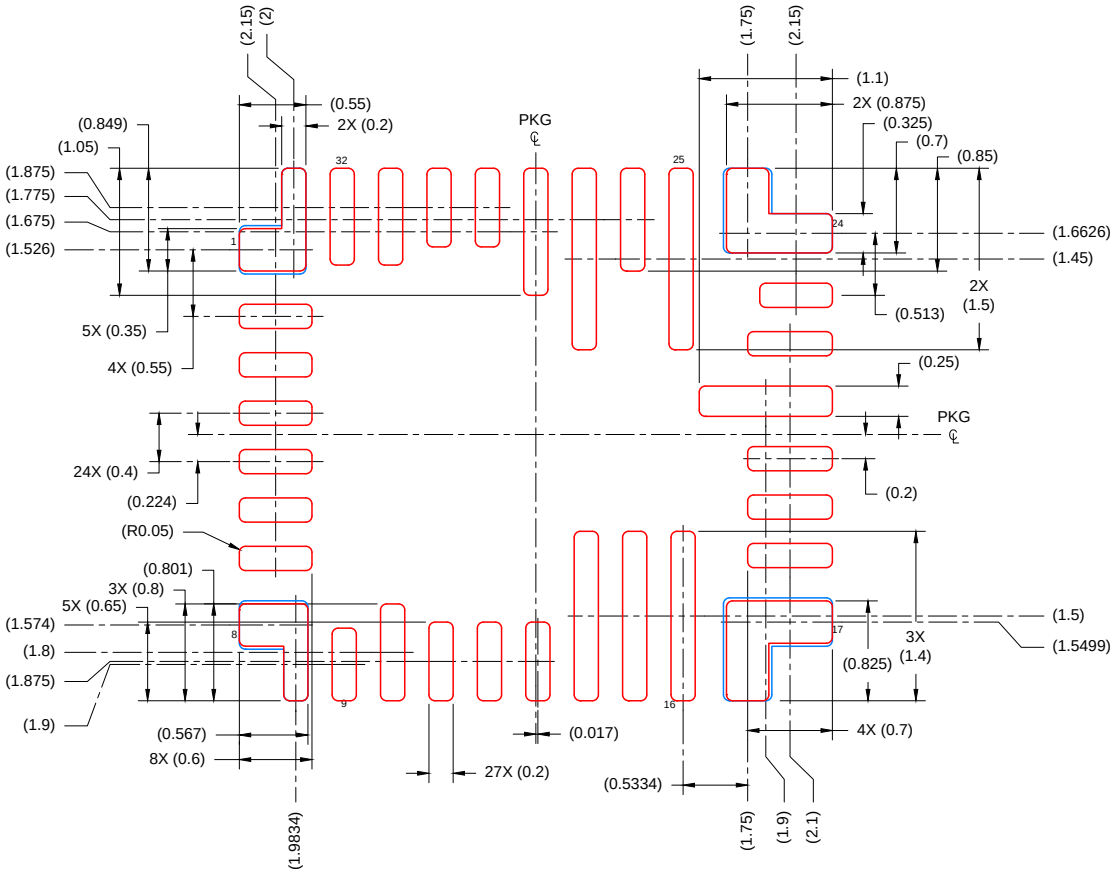


SOLDER MASK DETAILS

4226018/A 07/2020

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271) .
4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.100mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
PAD 1: 93% , PAD 8: 92%, PAD 17: 87%, PAD 24: 94%
SCALE: 16X

4226018/A 07/2020

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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